PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	ADG/21/12670
1.3 Title of PCN	STDxx (MOSFET Products in DPAK): Activation of TFME (TongFu former Nantong Fujitsu) as Second Source of Assembly and Final Testing
1.4 Product Category	see list
1.5 Issue date	2021-04-03

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Mario ASTUTI
2.1.2 Marketing Manager	Anna RANIOLO,Michele SCUTO
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Subcontractor TFME (TongFu former Nantong Fujitsu) - CHINA

4. Description of change

	Old	**New**
4.1 Description	ST Shenzhen - Assembly and Final testing	ST Shenzhen - Assembly and Final Testing Subcontractor TFME (TongFu former Nantong Fujitsu) - Assembly and Final Testing
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Capacity Increase
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes

7. Timing / schedule

7.1 Date of qualification results	2021-03-19
7.2 Intended start of delivery	2021-06-30
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	12670 Validation.zip		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2021-04-03

9. Attachments (additional documentations)

12670 Public product.pdf
12670 Validation.zip
12670 Details.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STD120N4F6	
	STD130N4F6AG	
	STD134N4F7AG	
	STD80N4F6	

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PRODUCT/PROCESS CHANGE NOTIFICATION

TITLE	**STDxxx (MOSFET Products in DPAK): Activation of TFME (TongFu former Nantong Fujitsu) as second source of Assembly and Final Testing**
IMPACTED PRODUCTS	see list
MANUFACTURING STEP	Assembly and Final Testing
INVOLVED PLANT	Subcontractor TFME (TongFu former Nantong Fujitsu) - China
CHANGE REASON	Capacity Increase
CHANGE DESCRIPTION	TFME (TongFu former Nantong Fujitsu) will be activated as second source of Assembly and Final Testing
TRACEABILITY	Internal traceability
VALIDATION	According to AEC-Q101 and ZVEI guidelines ZVEI change ID: SEM-PA-11 - Change of mold compound / encapsulation material SEM-PA-18 - Move all or part of production to a different assembly site SEM-TF-01 - Move all or part of electrical wafer test and/or final test to a different assembly site
REPORT	12670 Validation.zip

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : STDxx (MOSFET Products in DPAK): Activation of TFME (TongFu former Nantong Fujitsu) as Second Source of Assembly and Final Testing
PCN Reference : ADG/21/12670

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STD134N4F7AG	STD80N4F6	STD120N4F6
STD130N4F6AG		

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